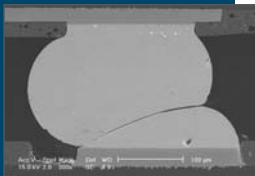
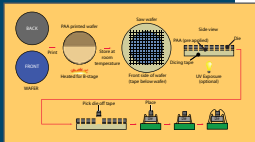
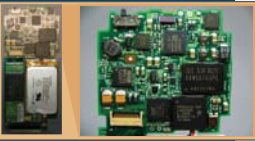


# Advanced Packaging Update: Market and Technology Trends

Q3, 2005



The third quarterly Advanced Packaging Update (formerly the BGA/CSP update) for 2005 features special coverage of packaging technology for Apple's new iPods. New developments in stacked die and stacked packages are discussed, including trends in die attach. Amkor's PoP is detailed. The report also provides information on the latest developments in memory module technology. Included are examples from IBM, Micron, Staktek, VCI, and 3D Plus. The report concludes with an update on a potential solution to the Pb-free solder dewetting problem.

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